Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1393	(bell and boyd and lloyd).att.	US-PGPUB; USPAT	OR	ON	2006/02/06 15:11
L3	12	(bell and boyd and lloyd).att. and transfer$4.ti.	US-PGPUB; USPAT	OR	ON	2006/02/06 15:14
L4	40	(bell and boyd and lloyd).att. and transfer$4.ab.	US-PGPUB; USPAT	OR	ON	2006/02/06 15:18
L5	13	(bell and boyd and lloyd).att. and (pressure adj (sensitiv$3 activat$3))	US-PGPUB; USPAT	OR	ON	2006/02/06 15:18
L7	8	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and ((strip$4 remov$4 peel$4) same (substrate$2 layer$2)) and (wire$2 wiring) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities) same conduct$3) and ((attach$3 embed$4 insert$3 press$3) same (device element electrode)) and (simple with matrix with display) and (active with matrix with display)	US-PGPUB; USPAT	OR	ON	2006/02/06 16:31
L8	25	("428" "156").clas. and (adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (simple with matrix with display) and (active with matrix with display)	US-PGPUB; USPAT	OR	ON	2006/02/06 16:34
L9	4	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and (conduct$3) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities)) and ((simple with matrix with display) same voltage) and ((active with matrix with display) same voltage)	US-PGPUB; USPAT	OR	ON	2006/02/06 16:37

L10	7	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and (conduct$3) and ((opening$3 via$2 holes cavity cavities)) and ((simple with matrix with display) same voltage) and ((active with matrix with display) same voltage)	US-PGPUB; USPAT	OR	ON	2006/02/06 16:37
S1	2504	("428" "156").clas. and (adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's")	US-PGPUB; USPAT	OR	ON	2006/02/06 16:34
S2	540	("428" "156").clas. and (adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3	US-PGPUB; USPAT	OR	ON	2006/02/02 15:08
S3	395	("428" "156").clas. and (adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and substrate$2	US-PGPUB; USPAT	OR	ON	2006/02/02 15:08
S4	80	("428" "156").clas. and (adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and substrate$2 and (red and blue and green)	US-PGPUB; USPAT	OR	ON	2006/02/02 15:15
S5	761	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and (red and blue and green) and conduct$4 and method. ti.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:26
S6	761	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and (red and blue and green) and method.ti.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:27

S7	360	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and (red and blue and green) and (harden cure$2 curing) and method.ti.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:33
S8	16	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and (red and blue and green) and (harden cure$2 curing) and "156".clas.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:34
S9	360	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (wire$3 wiring$2) and conduct$3 and (red and blue and green) and (harden cure$2 curing) and method.ti.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:51
S10	49	(adhesive$3 glue$3 sticky$3 adher$3) and (transfer$3) and ("light emitting diode" "LED" "LED's") and (red and blue and green) and (harden cure$2 curing) and "156".clas.	US-PGPUB; USPAT	OR	ON	2006/02/02 15:52
S11	7	("20050042391"|"3658616"|"5601884"|"5849857"|"5953091"|"6001277"|"6064524").PN.	US-PGPUB; USPAT	OR	ON	2006/02/03 08:38
S12	3971	(sony adj corporation).as. and device.ti.	US-PGPUB; USPAT	OR	ON	2006/02/03 08:38
S13	15	(sony adj corporation).as. and (device and transfer and method).ti.	US-PGPUB; USPAT	OR	ON	2006/02/03 08:41
S14	3	("20020096994"|"20030157741"|"20030162463").PN.	US-PGPUB; USPAT	OR	ON	2006/02/03 11:28
S15	6	((pressure with (sensitive activat$4) with adhesive) same ((thermal$3 heat) adj (sensitive acitvat$4))) and (device and transfer$4 and method).ab.	US-PGPUB; USPAT	OR	ON	2006/02/03 09:47
S16	3	((pressure with (sensitive activat$4) with adhesive) same ((thermal$3 heat) adj (sensitive acitvat$4))) and (element and transfer$4 and method).ab.	US-PGPUB; USPAT	OR	ON	2006/02/03 09:48
S17	44	((pressure with (sensitive activat$4) with adhesive) same ((thermal$3 heat) adj (sensitive acitvat$4))) and (transfer$4 and method).ab.	US-PGPUB; USPAT	OR	ON	2006/02/03 09:49

S18	21	((pressure with (sensitive activat$4) with adhesive) same ((thermal$3 heat) adj (sensitive acitvat$4))) and (transfer$4 and method).ti.	US-PGPUB; USPAT	OR	ON	2006/02/03 09:50
S19	1	((pressure with (sensitive activat$4) with adhesive) same ((thermal$3 heat) adj (sensitive acitvat$4))) and (transfer$4 and device).ti.	US-PGPUB; USPAT	OR	ON	2006/02/03 09:50
S20	0	"10511699"	US-PGPUB; USPAT	OR	ON	2006/02/03 11:29
S21	2521	doi.in.	US-PGPUB; USPAT	OR	ON	2006/02/03 11:29
S22	108	doi-masato.in.	US-PGPUB; USPAT	OR	ON	2006/02/03 11:39
S23	5	("4841194" | "4899081").PN. OR ("5426342").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 11:34
S24	33	S22 and transfer$4	US-PGPUB; USPAT	OR	ON	2006/02/03 11:44
S25	1	"20020096994"	US-PGPUB; USPAT	OR	ON	2006/02/03 13:29
S26	13	("20020115265"|"20020171089"|"5206749"|"5258320"|"5272326"|"5438241"|"5739800"|"6007664"|"6204079"|"6277711"|"6283693"|"6559905"|"6649012").PN.	US-PGPUB; USPAT	OR	ON	2006/02/03 14:42
S27	3453	(insulat$4 with ((polyamide acrylic) adj resin))	US-PGPUB; USPAT	OR	ON	2006/02/03 14:43
S28	812	(insulat$4 near3 ((polyamide acrylic) adj resin))	US-PGPUB; USPAT	OR	ON	2006/02/03 14:43
S29	9	(insulat$4 near3 ((polyamide acrylic) adj resin)) and "156".clas.	US-PGPUB; USPAT	OR	ON	2006/02/03 14:58
S30	575	(partially adj embedd$3) and ((device elements) with (transfer$4))	US-PGPUB; USPAT	OR	ON	2006/02/03 14:59
S31	7	(partially adj embedd$3) and ((device elements) with (transfer$4)).ti.	US-PGPUB; USPAT	OR	ON	2006/02/03 15:00
S32	93	(partially adj embedd$3) and ((device elements) with (transfer$4)).ab.	US-PGPUB; USPAT	OR	ON	2006/02/03 15:01
S33	91	(partially adj embedd$3) and ((device elements) with (transfer$4)) and (LED (light adj emitting adj diode))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:21
S34	1	(partially adj embedd$3) and ((transfer$4)).ti. and (LED (light adj emitting adj diode))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:22

S35	22	(partially adj embedd$3) and ((transfer$4)).ab. and (LED (light adj emitting adj diode))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:22
S36	33	(partially adj embedd$3) and ((transfer$4)).ti. and (LED (light adj emitting adj diode) piezoelectric transistor resistance diode)	US-PGPUB; USPAT	OR	ON	2006/02/03 15:34
S37	39	(partially near3 embedd$3) and ((transfer$4)).ti. and (LED (light adj emitting adj diode) piezoelectric transistor resistance diode)	US-PGPUB; USPAT	OR	ON	2006/02/03 15:35
S38	4	(partially near3 embedd$3) and ((transfer$4)).ti. and (LED (light adj emitting adj diode) piezoelectric transistor diode (liquid adj crystal))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:43
S39	4885	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and (conduct$3) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities))	US-PGPUB; USPAT	OR	ON	2006/02/06 16:34
S40	2262	("438").clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and (conduct$3) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:49
S41	3081	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and (conduct$3) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities)) and ((attach$3 embed$4 insert$3 press$3) same (device element electrode))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:52

S42	1627	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and (strip$4 remov$4 peel$4) and (wire$2 wiring) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities) same conduct$3) and ((attach$3 embed$4 insert$3 press$3) same (device element electrode))	US-PGPUB; USPAT	OR	ON	2006/02/03 15:53
S43	1407	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and ((strip$4 remov$4 peel$4) same (substrate$2 layer$2)) and (wire$2 wiring) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities) same conduct$3) and ((attach$3 embed$4 insert$3 press$3) same (device element electrode))	US-PGPUB; USPAT	OR	ON	2006/02/06 16:30
S44	116	("438" "156" "313" "445" "428"). clas. and ((substrate$2 layer$2) same (adhesive$2 adhere$2 resin$2 paste$2 glue$2)) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (harden$3 cur$3 solidify$3)) and ((strip$4 remov$4 peel$4) same (substrate$2 layer$2)) and (wire$2 wiring) and ((adhesive$2 adhere$2 resin$2 paste$2 glue$2) same (opening$3 via$2 holes cavity cavities) same conduct$3) and ((attach$3 embed$4 insert$3 press$3) same (device element electrode)) and (pressure adj (sensitive activat$3))	US-PGPUB; USPAT	OR	ON	2006/02/06 08:35
S45	13	("20020115265" | "20020171089" | "5206749" | "5258320" | "5272326" | "5438241" | "5739800" | "6007664" | "6204079" | "6277711" | "6283693" | "6559905" | "6649012").PN. OR ("6872635"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 08:26
S46	4071	"Semiconductor Energy Laboratory". as.	US-PGPUB; USPAT	OR	ON	2006/02/06 08:35

| S47 | 4 | "Semiconductor Energy Laboratory". as. and (transfer).ti. | US-PGPUB; USPAT | OR | ON | 2006/02/06 15:10 |